

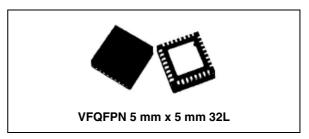
Push-pull four channel driver with diodes

Features

- 600 mA output current capability per channel
- 1.2 A peak output current (non repetitive) per channel
- Enable facility
- Overtemperature protection
- Logical "0" input voltage up to 1.5 V (high noise immunity)
- Internal clamp diodes

Description

The device is a monolithic integrated high voltage, high current four channel driver designed to accept standard DTL or TTL logic levels and drive inductive loads (such as relays solenoides, DC and stepping motors) and switching power transistors.

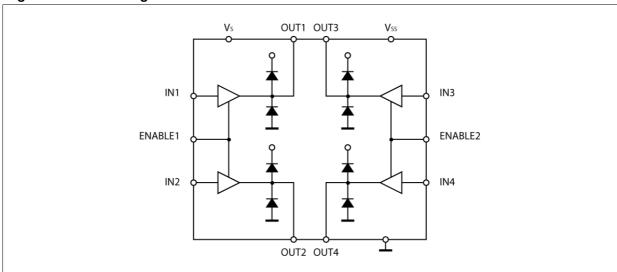


To simplify use as two bridges each pair of channels is equipped with an enable input. A separate supply input is provided for the logic, allowing operation at a lower voltage and internal clamp diodes are included.

This device is suitable for use in switching applications at frequencies up to 50 kHz.

The L2293Q is assembled in a VFQFPN-32L 5x5 package which has exposed pad available for heatsinking.

Figure 1. Block diagram



Contents L2293Q

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L2293Q Electrical data

1 Electrical data

1.1 Absolute maximum ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _S	Supply voltage	36	V
V _{SS}	Logic supply voltage	36	V
V _i	Input voltage	7	V
V _{en}	Enable voltage	7	V
Io	Peak output current (100 μs non repetitive)	1.2	Α
P _{tot}	Total power dissipation at T _{pins} = 90 °C	4	W
T _J	Junction temperature	150	°C
T _{STG}	Storage temperature	- 40 to 150	°C

1.2 Recommended conditions

Table 2. Recommended conditions

Symbol	Parameter		Value			
Syllibol			Тур	Max	Unit	
V _S	Supply voltage	V_{SS}		36	V	
V_{SS}	Logic supply voltage	2.8 (1)		36	V	
T_J	Junction temperature	-20 ⁽¹⁾		125	°C	

^{1.} See Figure 2

Electrical data L2293Q

1.3 Thermal data

Figure 2. Typical minimum logic supply voltage vs junction temperature

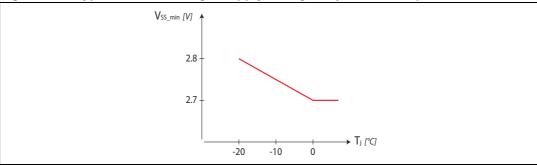


Table 3. Thermal data

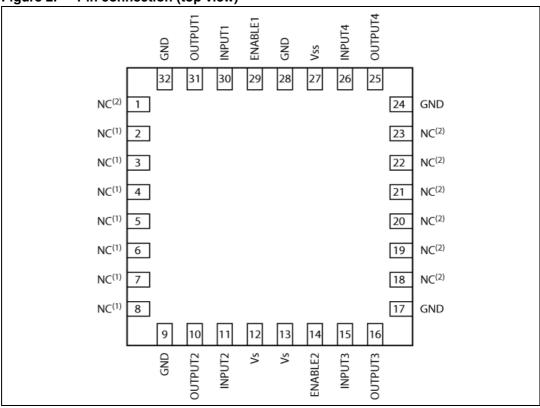
Symbol	Parameter	Value	Unit
R _{th(JA)}	Thermal resistance junction-ambient max. (1)	42	°C/W

Mounted on a double-layer FR4 PCB with a dissipating copper surface of 0.5 cm² on the top side plus 6 cm² ground layer connected through 18 via holes (9 below the IC).

L2293Q Pin connection

2 Pin connection

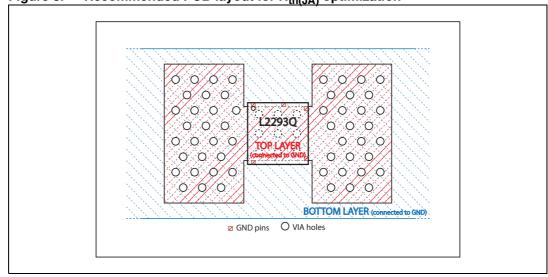
Figure 2. Pin connection (top view)



Note:

 $NC^{(1)}$ These NC pins are connected to the exposed PAD. The exposed PAD must be connected to GND pins. $NC^{(2)}$ These NC pins can be connected to GND pins and exposed PAD.

Figure 3. Recommended PCB layout for R_{th(JA)} optimization



Pin connection L2293Q

Table 4. Pin description

Pin n°	Name	Туре	Function	
1, 18, 19, 20, 21, 22, 23	NC		Not connected	
2, 3, 4, 5, 6, 7,	NC		Pins connected to the exposed PAD	
8, 9, 17, 24, 28, 32	GND		Ground	
10	OUTPUT2	0	Output 2	
11	INPUT2	I	Input 2	
12, 13	V _S		Supply voltage for the power output stages. A non-inductive 100 nF capacitor must be connected between these pins and ground.	
14	ENABLE2	I	Enable 2 input, the LOW state disables the Output 3 and Output 4.	
15	INPUT3	I	Input 3	
16	OUTPUT3	0	Output 3	
25	OUTPUT4	0	Output 4	
26	INPUT4	I	Input 4	
27	V _{SS}		Supply voltage for the logic blocks. A 100 nF capacitor must be connected between this pin and ground.	
29	ENABLE1	I	Enable 1 input, the LOW state disables the output 1 and Output 2.	
30	INPUT1	I	Input 1	
31	OUTPUT1	0	Output 1	

3 Electrical characteristics

For each channel, V_S = 24 V, V_{SS} = 5 V, T_A = 25 °C, unless otherwise specified.

Table 5. Electrical characteristics

Symbol	Pin	Parameter	Test condition	Min	Тур	Max	Unit	
			$V_i = L; I_O = 0; V_{en} = H$		2	6	mA	
I _S	12,13	Total quiescent supply current	$V_i = H; I_O = 0; V_{en} = H$		16	24	mA	
			V _{en} = L			4	mA	
	27		$V_i = L; I_O = 0; V_{en} = H$		44	60	mA	
I _{SS}		Total quiescent logic supply current	$V_i = H; I_O = 0; V_{en} = H$		16	22	mA	
			V _{en} = L		16	24	mA	
V _{IL}	11, 15, 26, 30	Input low voltage		- 0.3		1.5	V	
V _{IH}	11, 15,	Input high voltage	$V_{SS} \le 7 V$	2.3		V _{SS}	V	
IH	26, 30	26, 30 Input nigh vo	nput high voltage $V_{SS} > 7 \text{ V}$	V _{SS} > 7 V	2.3		7	V
I _{IL}	11, 15, 26, 30	Low voltage input current	V _{IL} = 1.5 V			- 10	μА	
I _{IH}	11, 15, 26, 30	High voltage input current	$2.3 \text{ V} \le \text{V}_{IH} \le \text{V}_{SS} - 0.6 \text{ V}$		30	100	μА	
V _{en L}	14, 29	Enable low voltage		- 0.3		1.5	V	
V	14.00	Enable high voltage	$V_{SS} \le 7 V$	2.3		V _{SS}	V	
V _{en H}	14, 29	Enable high voltage	V _{SS} > 7 V	2.3		7	V	
I _{en L}	14, 29	Low voltage enable current	V _{en L} = 1.5 V		- 30	- 100	μА	
I _{en H}	14, 29	High voltage enable current	$2.3 \text{ V} \le \text{V}_{en H} \le \text{V}_{SS} - 0.6 \text{ V}$			± 10	μА	
V _{CE(sat)H}	10, 16, 25, 31	Source output saturation voltage	I _O = - 0.6 A		1.4	1.8	V	
V _{CE(sat)L}	10, 16, 25, 31	Sink output saturation voltage	I _O = + 0.6 A		1.2	1.8	V	
V _F		Clamp diode forward voltage	I _O = 600 nA		1.3		٧	

Electrical characteristics L2293Q

 $\rm V_S = 24$ V, $\rm V_{SS} = 5$ V, $\rm T_A = 25~^{\circ}C,$ unless otherwise specified.

Table 6. AC operation

Symbol	Parameter	Test condition	Min	Тур	Max	Unit
^t r	Rise time ⁽¹⁾	0.1 to 0.9 V _O		250		ns
t _f	Fall time ⁽¹⁾	0.9 to 0.1 V _O		250		ns
t _{on}	Turn-on delay (1)	0.5 V _i to 0.5 V _O		750		ns
t _{off}	Turn-off delay ⁽¹⁾	0.5 V _i to 0.5 V _O		200		ns

^{1.} See Figure 4

Figure 4. Switching times

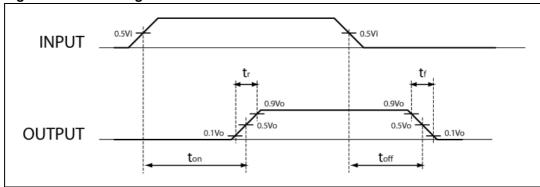


Table 7. Truth table (one channel)

Input	Enable ⁽¹⁾	Output
Н	Н	Н
L	Н	L
Н	L	Z ⁽²⁾
L	L	Z ⁽²⁾

^{1.} Relative to the considered channel

^{2.} Z = High output impedance

4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. VFQFPN 5x5x1.0 32L pitch 0.50

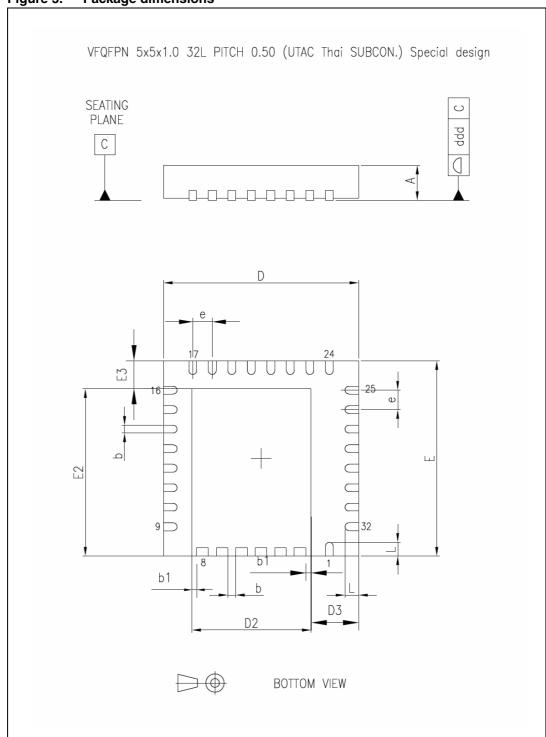
Dim		Databook (mm)	
Dim.	Min	Тур	Max
Α	0.80	0.85	0.95
b	0.18	0.25	0.30
b1	0.165	0.175	0.185
D	4.85	5.00	5.15
D2	3.00	3.10	3.20
D3	1.10	1.20	1.30
Е	4.85	5.00	5.15
E2	4.20	4.30	4.40
E3	0.60	0.70	0.80
е		0.50	
L	0.30	0.40	0.50
ddd			0.08

Note: 1 VFQFPN stands for thermally enhanced very thin profile fine pitch quad flat package no lead. Very thin profile: $0.80 < A \le 1.00$ mm.

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² Details of terminal 1 are optional but must be located on the top surface of the package by using either a mold or marked features.

Figure 5. Package dimensions



L2293Q Order codes

5 Order codes

Table 9. Order code

Order code	Package	Packaging
L2293Q	VFQFPN 5x5x1.0 32L	Tube

Revision history L2293Q

6 Revision history

Table 10. Document revision history

Date	Revision	Changes
10-Jul-2008	1	First release
26-Feb-2009	2	Updated Table 3 on page 4
12-Aug-2009	3	Updated description in coverpage

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